100% Material Declaration Data Sheet FG900

Average Weight: 4.2 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					**0.119328**	**2.84%**
	Silicon	7440-21-3	100.00		0.119328	
Die Attach Material					**0.0105**	**0.25%**
	Silver	7440-22-4	78.00		0.00819	
	Resin	Trade Secret	22.00		0.00231	
Mold Compound					**1.73292**	**41.26%**
	Epoxy Resins	Trade Secret	6.00		0.1039752	
	Phenolic Resins	Trade Secret	6.00		0.1039752	
	Carbon Black	1333-86-4	0.50		0.0086646	
	SiO2 Filler	60676-86-0	84.00		1.4556528	
	Bismuth	7440-69-9	Max. 1.00		0.0173292	
	Metal Hydroxide	Trade Secret	2.50	Filler	0.043323	
Laminate					**1.48386**	**35.33%**
	Bismaleimide/Triazine Board	13676-54-5/25722-66-1	17.63		0.261604518	
	Epoxy	29690-82-2	10.59		0.157140774	
	Glass Fiber (GF)	65997-17-3	15.72		0.233262792	
	Copper	7440-50-8	49.01	Metal Layer	0.727239786	
	Nickel	7440-02-0	1.32	Metal Layer	0.019586952	
	Gold	7440-57-5	0.23	Metal Layer	0.003412878	
	Brominated Resin	68541-56-0	5.50	Flame Retardant	0.0816123	
Bond Wire					**0.0189**	**0.45%**
	Gold	7440-57-5	100.00		0.0189	
Solder Balls					**0.83454**	**19.87%**
	Tin	7440-31-5	63.00		0.5257602	
	Lead	7439-92-1	37.00		0.3087798	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
9/21/06	1.0	Initial release.